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TITLE : ELECTROLESS COPPER PLATING SOLUTION

ABSTRACT : PURPOSE: To prevent blister of a through hole base material and to improve plating appearance, depositing rate and liquid stability by adding an iodine compound and  $\alpha,\alpha'$ -dipyridyl into an electroless copper plating solution.

CONSTITUTION: The electroless copper plating solution consists of an aqueous solution, containing of a cupric salt, a complexing agent, a reducing agent and a pH controlling agent such as alkali hydroxide, as a basic composition. Furthermore, the iodine compound and  $\alpha,\alpha'$ -dipyridyl are added into the basic composition. Conc. of the iodine compound in the plating solution is preferably 5-100mg/l and conc. of  $\alpha,\alpha'$ -dipyridyl is preferably 5-100mg/l. The deposited copper low in plating deposit stress is obtained by the electroless copper plating solution composition.

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